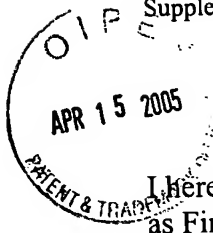
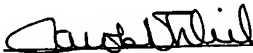


Atty. Docket No.: 10116-102DIV2  
Appl. Serial No.: 10/824,723  
Supplemental Response



**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313 on April 13, 2005.

  
Jacob N. Erlich  
Reg. No. 24,338

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants:	L. Pierre deROCHEMONT, <i>et al.</i>	Examiner:	Donghai D. NGUYEN
Serial No:	10/824,723	Art Unit:	3729
Filed:	April 15, 2004		
For:	METHOD OF MANUFACTURE OF CERAMIC COMPOSITE WIRING STRUCTURES FOR SEMICONDUCTOR DEVICES		

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To: Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**Supplemental Response in Accordance with Telephone Interview of April 8, 2005**

Dear Sir:

This supplemental response is being provided in response to the telephone interview of April 8, 2005 for the above-captioned U.S. patent application. No fees are believed necessary for consideration of this paper. If the payment of such fees are deemed necessary, however, such fees are hereby authorized to be charged to our Deposit Account No. 03-2410, Order No. 10116-102.